

ABSTRACT

A silicone rubber adhesive composition comprising (A)
5 a heat curable organopolysiloxane composition of the
addition curing type or peroxide curing type, (B)
reinforcing silica fines, and (C) an organic compound or
10 organosilicon compound having an epoxy equivalent of 100-
5,000 g/mol and containing at least one aromatic ring in a
molecule is easily moldable within a short time by injection
molding, suitable in primerless molding, and bondable with
various thermoplastic resins. Integrally molded articles in
which the silicone rubber adhesive composition is firmly
15 bonded to the thermoplastic resin are obtainable without a
need for modification of the resin.

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